# AD6973D Datasheet

# Zhuhai Jieli Technology Co.,LTD

Version: 3.1

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### AD6973D4 Features

#### **CPU**

- 32-bit DSP supports hardware Float Point Unit(FPU)
- Up to 160MHz programmable processor
- 64Vectored interrupts
- 8 Levels interrupt priority

#### **DSP Audio Processing**

- SBC, AAC Audio decodes supported for BT audio
- mSBC voice codec supported for BT phone
- Supports MP2, MP3, WMA, APE, FLAC, AAC, MP4, M4A, WAV, AIF, AIFC audio decoding
- Packet Loss Concealment (PLC) for voice processing
- Acoustic echo cancellation/suppression (AEC,AES)
- Single/Dual analog/digital MIC
   Environmental Noise Cancellation (ENC)
- Multi-band DRC limiter
- 20-band EQ configuration for voice Effects

#### **Audio Codec**

- Two channels 24-bit DAC, SNR >= 101dB
- Two channels 24-bit ADC, SNR >= 85dB
- Sampling rates of 8KHz/11.025KHz/16KHz/22.05KHz/24KHz/32KHz/44.1KHz/48KHz are supported
- One analog MIC amplifier, build-in MIC bias generator
- Supports two PDM digital MIC inputs
- One channel Stereo analog MUX
- Supports cap-less, single-ended, and differential mode at the DAC path
- Supports 16ohm and 32ohm Speaker loading

# (QDID: 223418)

- Meet class2 and class3 transmitting power requirement
- Support GFSK and π/4 DQPSK all packet types
- Provides maximum +8dbm transmitting nower
- receiver with minimum -94dBm sensitivity
- Fast AGC for enhanced dynamic range
- Support a2dp\avctp\avdtp\avrcp\hfp\spp\smp\
  att\gap\gatt\rfcomm\sdp\l2cap profile
- a2dp 1.4\avctp 1.4\avdtp 1.3\ avrvp 1.6.2\hfp 1.8 \spp 1.2\rfcomm 1.2\pnp 1.3\hid 1.1.1\sdp core5.4\l2cap core 5.4

#### **Peripherals**

- One full speed USB 2.0 OTG controller
- Six multi-function 32-bit timers, support capture and PWM mode
- Three full-duplex basic UART, support DMA
- One hardware IIC interface supports host and device mode
- Two Built-in low power Cap Sense Keys
- Built-in Cap Sense Key controller
- 10-bit ADC for analog sampling
- External wake up/interrupt on all GPIOs

#### **PMU**

- Low voltage LDO and DC-DC for internal digital and analog circuit supply
- 2uA current consumption in the soft-off mode
- Built-in LDO and DC-DC for the core, I/O, Bluetooth and flash
- VBAT is 2.2V to 4.5V
- VDDIO is 2.2V to 3.4V

#### **Packages**

QFN20(3mm\*3mm)

#### Bluetooth

Compliant with Bluetooth
 V5.4+BR+EDR+BLE specification

### Confidential

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### **Temperature**

Operating temperature: -40°Cto+85°C

Storage temperature: -65°C to +150°C

### **Applications**

Bluetooth TWS headsets

2.4G wireless MIC



# 1. Pin Definition

### 1.1 Pin Assignment

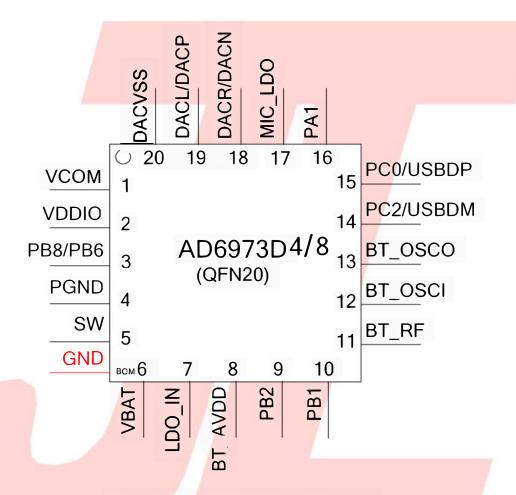


Figure 1-1 AD6973D Package Diagram

# 1.2 Pin Description

Table 1-1 AD6973D Pin Description

PIN NO.	Name	I/O Type	Drive (mA)	Function	Other Function
1	VCOM	P	/		DAC reference voltage
2	VDDIO	P	/		IO Power 3.3v
2	PB8	I/O	8/24	GPIO	MIC1: MIC1 Input Channel;  UART0RXB: Uart0 Data Input(B);  CAP4: Timer4 Capture;
3	PB6	I/O	8/24	GPIO	UART1RXA: Uart1 Data Input(A);  PWM2: Timer2 PWM Output;  ADC9: ADC Input Channel 9;  Touch7: Touch Input Channel 7;
4	PGND	P	/	7/	DCDC Ground
5	SW	P	1	DCDC output	DCDC switch output, connected to inductor
6	VBAT	P	/	7 /	connect to battery
7	LDO_IN	P	,		Charge Power Input; UART0TXC: Uart0 Data Output(C); UART0RXC: Uart0 Data Input(C); PWM3: Timer3 PWM Output; CAP1: Timer1 Capture;
8	BT_AVDD	P	/	7 /	BT Power
9	PB2	I/O	8/24	GPIO	UART2RXC: Uart2 Data Input(C); SPI2DOC: SPI2 Data Out(C); CAP5: Timer5 Capture; ADC7: ADC Input Channel 7; LP_TH1: Low Power Touch Channel 1
10	PB1	I/O	8/24	GPIO (pull up)	Long Press Reset; SPI2CLKC: SPI2 Clk(C); UART2TXC: Uart2 Data Output(C) ADC6: ADC Input Channel 6; LP_TH0: Low Power Touch Channel 0
11	BT_RF	/	/		BT Antenna
12	BT_OSCI	I	/		BTOSC In
13	BT_OSCO	О	/		BTOSC Out
14	PC2	I/O	8/24		IIC_SCL_C: IIC SCL(C); UART0TXD: Uart0 Data Output(D); TMR1: Timer1 Clock Input;

	USBDM	I/O	4	USB Negative Data	UART1RXD: Uart1 Data Input(D); IIC_SDA_A: IIC SDA(A); ADC11: ADC Input Channel 11;	
15	USBDP	I/O	4	USB Positive Data	UART1TXD: Uart1 Data Output(D); IIC_SCL_A: IIC SCL(A); ADC10: ADC Input Channel 10;	
	PC0	I/O	8	GPIO	UART1TXB: Uart1 Data Output(B);	
16	PA1	I/O	8/24	GPIO	MIC0: MIC0 Input Channel; PWM0: Timer0 PWM Output; UART1TXC: Uart1 Data Output(C);	
17	MIC_LDO	P	/		MIC Power	
18	DACR/DACN	О	/		DAC Right Channel  Different DAC Negative Channel	
19	DACL/DACP	О	/		DAC Left Channel Different DAC Positive Channel	
20	DACVSS	P	1	7/4	Analog Ground	



## 2. Electrical Characteristics

## 2.1 Absolute Maximum Ratings

Table 2-1

Symbol	Parameter	Min	Max	Unit
Tamb	Ambient Temperature	-40	+85	°C
Tstg	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	4.5	V
LDO_IN	Charger Voltage	-0.3	6	V
V <sub>3.3IO</sub>	3.3V IO Input Voltage	-0.3	3.6	V

Note: The chip can be damaged by any stress in excess of the absolute maximum ratings listed below

### 2.2 PMU Characteristics

Table 2-2

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
VBAT	Voltage Input	2.2	3.7	4.2	V	
	Charger supply	/				
LDO_IN	Voltage	4.5	5.0	5.5	V	
Normal mode	7					
VDDIO	Voltage output	_	3.0	_	V	VBAT = 4.2V, 10mA loading
VDDIO	Loading current	_	4	100	mA	VDDIO=3V@VBAT = 4.2V
DT AVDD	Voltage output	_	1.3	_	V	VDDIO=3.0V, 10mA loading
BT_AVDD	Loading current	_	/ _/	60	mA	BT_AVDD=1.25V@VDDIO=3.0v
LP mode		37				
VDDIO	Loading current	332		5	mA	VDDIO=3V@VBAT = 4.2V

# 2.3 Battery Charge

**Table 2-3** 

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
LDO_IN	Charge Input Voltage	4.5	5	5.5	V	-
V	Chana Valea	4.15	4.2	4.25	V	LDO_IN>4.5V
V <sub>Charge</sub>	Charge Voltage	4.30	4.35	4.40	V	LDO_IN>4.65V

I <sub>Charge</sub>	Charge Current	20		200	mA	Charge current at fast charge mode
${ m I}_{ m Trikl}$	Trickle Charge Current	20	45	70	mA	$ m V_{BAT}{<}V_{Trikl}$

# 2.4 IO Input/Output Electrical Logical Characteristics

Table 2-4

IO input ch	IO input characteristics								
Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions			
$V_{\rm IL}$	Low-Level Input Voltage	-0.3	_	0.3* VDDIO	V	VDDIO = 3.3V			
$ m V_{IH}$	High-Level Input Voltage	0.7* VDDIO	-	VDDIO+0.3	V	VDDIO = 3.3V			
IO output o	characteristics			7 ./					
$V_{OL}$	Low-Level Output Voltage	-/	-	0.33	V	VDDIO = 3.3V			
$V_{\mathrm{OH}}$	High-Level Output Voltage	2.7	- //	_	V	VDDIO = 3.3V			

### 2.5 Internal Resistor Characteristics

Table 2-5

Port	General Output	High Drive	Internal Pull-Up Resistor	Internal Pull-Down Resistor	Comment
PA1, PB1,PB2, PB6,PB8, PC2	8mA	24mA	10K	10K	1、PB1 default pull up 2、USBDM & USBDP default pull
PC0	8mA	-	10K	10K	down 3 internal pull-up/pull-down
USBDP	4mA	- 55	1.5K	15K	resistance   accuracy ±20%
USBDM	4mA	_	180K	15K	

### 2.6 DAC Characteristics

Table 2-6

Parameter	Min	Тур	Max	Unit	Test Conditions
Frequency Response	20	_	20K	Hz	
THD+N	_	-80	_	dB	1KHz/0dB
S/N	_	101	_	dB	10Kohm loading
Crosstalk	_	-80	_	dB	With A-Weighted Filter
Output Swing		0.45		Vrms	
Dynamic Range		90		dB	1KHz/-60dB

					10Kohm loading
					With A-Weighted Filter
DAC Output Power	_	4	_	mW	32ohm loading

### 2.7 ADC Characteristics

Table 2-7

Parameter	Min	Тур	Max	Unit	Test Conditions
Dynamic Range		85		dB	Fsample=44.1kHz Fin=1KHz 2mVpp Input
S/N	_	85	7_/	dB	F 1 44 11 II
THD+N	_	-60	/ _/	dB	Fsample=44.1kHz
Crosstalk	_ /	-80		dB	Fin=1KHz 1.2Vpp Input

### 2.8 BT Characteristics

### 2.8.1 Transmitter

**Basic Data Rate** 

Table 2-8

Busic Butu Rate		Tubic 2				
Paramete	r	Min	Тур	Max	Unit	Test Conditions
RF Transmit P	RF Transmit Power		6	8	dBm	
RF Power Contro	l Range		20		dB	25℃,
20dB Bandw	20dB Bandwidth		950		KHz	Power Supply
	+2MHz		-40		dBm	
Adjacent Channel	-2MHz		-38	7	dBm	VBAT=5V
Transmit Power	+3MHz		-44		dBm	2441MHz
	-3MHz		-35		dBm	

### **Enhanced Data Rate**

**Table 2-9** 

Parameter		Min	Тур	Max	Unit	Test Conditions
Relative Power			-1		dB	
-/4 DODSV	DEVM RMS		6		%	
π/4 DQPSK  Modulation Accuracy	DEVM 99%		10		%	25℃,
	DEVM Peak		15		%	Power Supply
	+2MHz		-40		dBm	VBAT=5V
Adjacent Channel	-2MHz		-38		dBm	2441MHz
Transmit Power +3MHz			-44		dBm	
	-3MHz		-35		dBm	

### 2.8.2 Receiver

### **Basic Data Rate**

**Table 2-10** 

Parameter		Min	Тур	Max	Unit	Test Conditions
Sensitivity			-92		dBm	
Co-channel Interferen	nce Rejection		-13		dB	
	+1MHz		+5		dB	25℃,
	-1MHz		+2		dB	Power Supply
Adjacent Channel	+2MHz		+37		dB	VBAT=5V
Interference Rejection	-2MHz		+36		dB	2441MHz
	+3MHz		+40		dB	
	-3MHz		+35		dB	

### **Enhanced Data Rate**

**Table 2-11** 

Parameter		Min	Тур	Max	Unit	Test Conditions
		112111				2 cot conditions
Sensitivit	У		-94		dBm	
Co-channel Interferer	nce Rejection		-13		dB	
	+1MHz		+5		dB	25℃,
	-1MHz		+2		dB	Power Supply
Adjacent Channel	+2MHz	N.	+37		dB	VBAT=5V
Interference Rejection	-2MHz		+36	Y	dB	2441MHz
	+3MHz		+40		dB	
	-3MHz	7/	+35		dB	

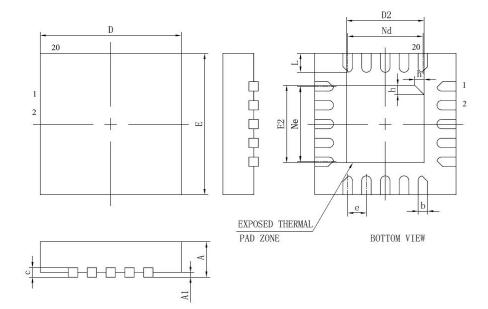
## 2.9 ESD Protection

Parameter	Тур.	Test pin	Reference standard
Human Body Mode	±4KV	All pins	JEDEC EIA/JESD22-A114
Machine Mode	$\pm 200 V$	All pins	JEDEC EIA/JESD22-A115
Charge Device Model	±1KV	All pins	JEDEC EIA/JESD22-C101F
Lotale yea	±200mA	All GPIO pins	JEDEC STANDARD NO.78E
Latch up	1.5xVopmax	All power pins	JEDEC STANDARD NO./8E

Note: 1.5xVopmax = 1.5 times maximum operating voltage

# 3. Package Information

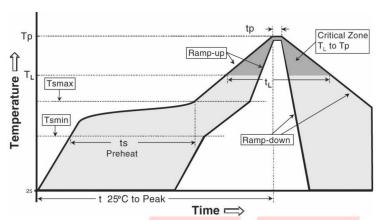
# 3.1 QFN20\_3.0x3.0



SYMBOL	MILLIMETER				
STMBOL	MIN	NOM	MAX		
A	0.70	0.75	0.80		
A1	-	0.02	0.05		
b	0. 15	0. 20	0. 25		
c	0.18	0. 20	0. 25		
D	2. 90	3.00	3. 10		
D2	1.55	1, 65	1. 75		
e	0. 40BSC				
Ne	1. 60BSC				
Nd		1. 60BSC			
Е	2. 90	3. 00	3. 10		
E2	1.55	1.65	1. 75		
L	0.35	0.40	0.45		
h	0. 20	0. 25	0.30		
L/F载体尺寸 (NF.1)		75*75			



# 4. Solder-Reflow Condition



**Figure 5-1 Classification Reflow Profile** 

### **Classification Profiles**

Table 5-1

	Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
	Temperature Min (T <sub>smin</sub> )	100℃	150℃
Preheat	Temperature Max (T <sub>smax</sub> )	150℃	200℃
/Soak	Time (ts) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-180 seconds
Average	ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )	3°C/second max	3 ℃/second max
Liquidous temperature (T <sub>L</sub> )		183℃	217℃
Time (t <sub>L</sub> ) maintained above T <sub>L</sub>		60-150 seconds	60-150 seconds
Peak package body temperature (Tp)		See Table 5-2	See Table 5-3
	hin 5°C of actual pperature (tp)²	10-30 seconds	20-40 seconds
Ramp-do	wn rate (T <sub>p</sub> to T <sub>L</sub> )	6°C/second max	6°C/second max
Time 25°	C to peak temperature	6 minutes max	8 minutes max

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within  $5^{\circ}$ C of actual peak temperature (tp) specified for the reflow profiles is a "supplier" minimum and "user" maximum.

**SnPb - Classification Temperature** 

**Table 5-2** 

Package Thickness	Volume mm³ < 350	Volume mm³  ≥ 350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

### **Pb-free - Classification Temperature**

#### Table 5-3

Package Thickness	Volume mm <sup>3</sup> < 350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> > 2000
< 1.6mm	260℃	260℃	260℃
1.6 mm - 2.5mm	260℃	250℃	245℃
> 2.5mm	250℃	245℃	245℃



# **5.** Revision History

Date	Revision	Description			
2020.08.18	V2.0	Initial Release			
2020.10.12	V2.1	Update PMU characteristics			
2020.10.12	V 2.1	Add Bluetooth profiles version number			
2021.07.21	V2.2	Update Bluetooth characteristics, Charge characteristics, Audio			
2021.07.21	<b>V</b> 2.2	characteristics			
2021.08.09	V2.3	Update Package Information			
2021.10.22	V2.4	Update Bluetooth Vision and profiles			
2022.01.10	V2.5	Add Chip ESD Protection Characteristics			
2022.05.16	V3.0	Update DAC PIN Define, Audio ADC characteristics			
2022.03.10	V 3.0	Add Chip Solder-Reflow Condition			
2023.10.20	V3.0	Update AD6973D BT_Features & Applications			

